



2826

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: ZHENG, et al. Examiner: Andújar, L.
Serial No.: 09/775,370 Group Art Unit: 2826
Filed: February 1, 2001 Docket No.: NEW: PHA 51108A
OLD: VLSI.225DIV1
Title (new): SEMICONDUCTOR DEVICE COMPRISING ALUMINUM-BASED PLUGS

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this communication is being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on May 31, 2002.

By:

Kelly S. Waltigney

OFFICE ACTION RESPONSE

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated February 27, 2002, please consider the following amendment and remarks:

In the Specification

Please amend the specification as follows; a marked-up version of the amendments is attached hereto as an Appendix:

On page 1, line 1, replace the title as follows:

SEMICONDUCTOR DEVICE COMPRISING ALUMINUM-BASED PLUGS

On page 14, line 7, replace the paragraph with the following:

Referring to FIG. 2D, according to one embodiment of the present invention, to prevent recess formation in the non-overlapping portions of the via structures during the over etch process of the aluminum alloy metal lines, an example process 400 as outlined in FIG. 3 may be followed. In one particular implementation, the dielectric layer 230 includes a portion 236

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